SDAS206A - APRIL 1982 - REVISED DECEMBER 1994

- Permit Multiplexing From n Lines to One Line
- Perform Parallel-to-Serial Conversion
- Strobe (Enable) Line Provided for Cascading (n Lines to n Lines)
- 'ALS253 and SN74AS253A Are 3-State Versions of These Parts
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

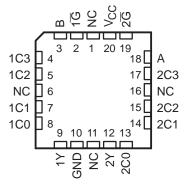
These dual 1-of-4 data selectors/multiplexers contain inverters and drivers to supply full binary decoding data selection to the AND-OR gates. Separate strobe (\overline{G}) inputs are provided for each of the two 4-line sections.

The SN54ALS153 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74ALS153 and SN74AS153 are characterized for operation from 0°C to 70°C.

SN54ALS153 . . . J PACKAGE SN74ALS153, SN74AS153 . . . D OR N PACKAGE (TOP VIEW)

,		VIL	,		
1G [B [1C3 [1C2 [1C1 [1C0 [1Y [GND]	2 3 4 5 6 7	υ	14 13 12 11		V <u>C</u> C 2G A 2C3 2C2 2C1 2C0 2Y
	Ľ		Ũ	٢	

SN54ALS153 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

		INP	UTS			070005			
SEL	ECT		DA	TA		STROBE G	OUTPUT		
В	Α	C0	C1	C2	C3	Ŭ	I		
Х	Х	Х	Х	Х	Х	Н	L		
L	L	L	Х	Х	Х	L	L		
L	L	Н	Х	Х	Х	L	Н		
L	Н	Х	L	Х	Х	L	L		
L	н	Х	Н	Х	Х	L	н		
н	L	Х	Х	L	Х	L	L		
н	L	Х	Х	Н	Х	L	Н		
н	Н	Х	Х	Х	L	L	L		
н	Н	Х	Х	Х	Н	L	н		

FUNCTION TABLE

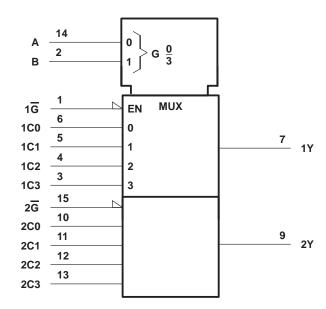
Select inputs A and B are common to both sections.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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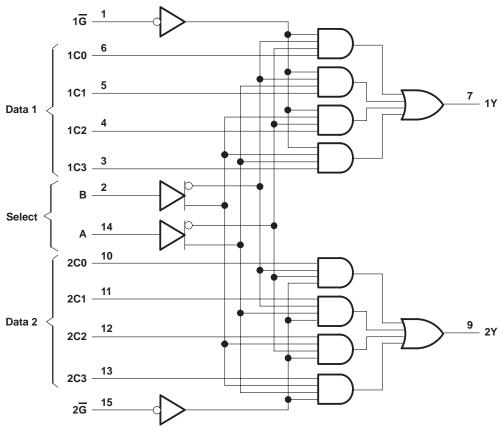
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Operating free-air temperature range, T _A :	SN54ALS153	–55°C to 125°C
	SN74ALS153	0°C to 70°C
Storage temperature range		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS153		SN74ALS153			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-1			-2.6	mA
IOL	Low-level output current			12			24	mA
ТА	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	7507.0	TEST CONDITIONS		54ALS1	53	SN	74ALS1	53	
PARAMETER	TEST C			TYP‡	MAX	MIN	typ‡	MAX	UNIT
VIK	V _{CC} = 4.5 V,	l _l = – 18 mA			-1.5			-1.5	V
	V_{CC} = 4.5 V to 5.5 V,	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		
VOH		$I_{OH} = -1 \text{ mA}$	2.4	3.3					V
	V _{CC} = 4.5 V	$I_{OH} = -2.6 \text{ mA}$				2.4	3.2		
		I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
V _{OL}	$V_{CC} = 4.5 V$	I _{OL} = 24 mA					0.35	0.5	V
lį	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
ΙIΗ	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
١ _١ ٢	V _{CC} = 5.5 V,	VI = 0.4 V			-0.1			-0.1	mA
١ _O §	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
ICC	V _{CC} = 5.5 V,	All inputs at 4.5 V		7.5	14		7.5	14	mA

[‡] All typical values are at V_{CC} = 5 V, $T_A = 25^{\circ}C$.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL	= 50 pl = 500 0 = MIN t	V to 5.5 , 2, o MAX [†] SN74A		UNIT
			MIN	MAX	MIN	MAX	
tPLH			5	29	5	21	
^t PHL	A or B	Y	5	27	5	21	ns
^t PLH	Data	N N	3	15	3	10	
^t PHL	(any C)	Y	2	18	4	15	ns
^t PLH	G	v	5	27	5	18	ns
^t PHL	6	T	3	22	5	18	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	V
Input voltage, V ₁	V
Operating free-air temperature range, T _A : SN74AS153 0°C to 70°	С
Storage temperature range	С

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN74AS153			
		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
IOH	High-level output current			-15	mA
IOL	Low-level output current			48	mA
Т _А	Operating free-air temperature	0		70	°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED								
	PARAMETER	TEST CONE	DITIONS	MIN	MIN TYP [†] MAX		UNIT	
VIK		V _{CC} = 4.5 V,	lj = – 18 mA			-1.2	V	
		$V_{CC} = 4.5 V \text{ to } 5.5 V,$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2				
VOH	[V _{CC} = 4.5 V,	I _{OH} = – 15 mA	2.4	3.2		V	
VOL		V _{CC} = 4.5 V,	I _{OL} = 48 mA		0.35	0.5	V	
	А, В		N/ - N/			0.2		
Ц	All others	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1	mA	
	А, В					40		
ЧΗ	All others	V _{CC} = 5.5 V,	V _I = 2.7 V			20	μA	
	А, В					-1		
ΊL	All others	$V_{CC} = 5.5 V,$.5 V, V _I = 0.4 V			-0.5	mA	
10‡		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	mA	
ІССН		V _{CC} = 5.5 V			16	26	mA	
ICCL		V _{CC} = 5.5 V			21	33	mA	

[†] All typical values are at V_{CC} = 5 V, T_A = 25° C.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

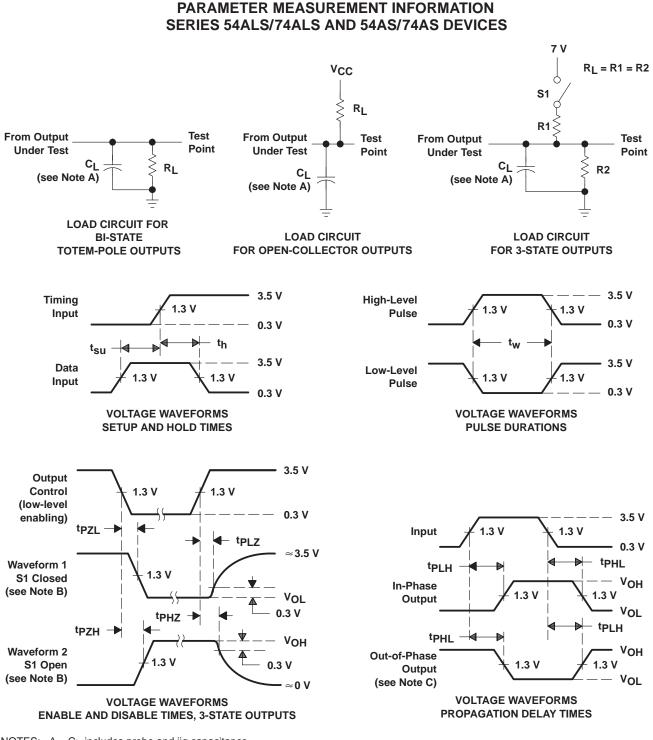
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	ТО (OUTPUT)	R _L = 500 : T _A = MIN SN74	$V_{CC} = 4.5 V \text{ to } 5.5 V,$ $C_{L} = 50 \text{ pF},$ $R_{L} = 500 \Omega,$ $T_{A} = \text{MIN to MAX}$ $\overline{SN74AS153}$ $\overline{MIN} MAX$	
tPLH			3	12.5	
tPHL	A or B	Y	3	11	ns
^t PLH	Data		2	7	
^t PHL	(any C)	Y	2	8	ns
^t PLH	G	×	3	11.5	200
^t PHL	5	Ĩ	10	9	ns

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_f = t_f = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



TEXAS INSTRUMENTS www.ti.com

18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
84134012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8413401EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
8413401FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54ALS153J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74ALS153D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS153DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS153DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS153DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS153DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS153DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS153N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS153NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS153NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS153NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS153NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS153D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS153DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS153DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS153DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS153DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS153DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS153N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS153NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS153NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS153NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS153NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM



Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SNJ54ALS153J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54ALS153W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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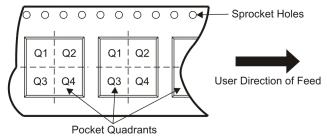
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS153DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS153NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS153DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AS153NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

19-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS153DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74ALS153NSR	SO	NS	16	2000	346.0	346.0	33.0
SN74AS153DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74AS153NSR	SO	NS	16	2000	346.0	346.0	33.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK

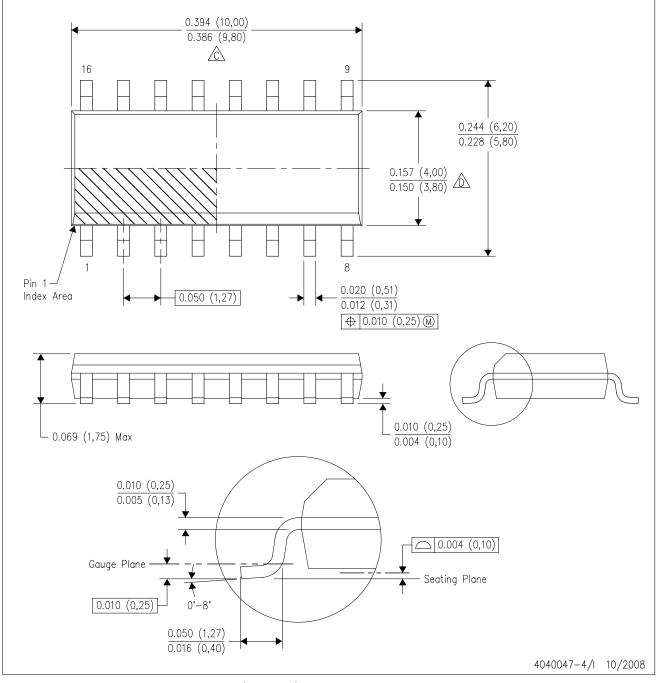


- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



D(R-PDSO-G16)



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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